

S/N 09/484303

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Kie Y. Ahn et al.

Examiner: Neal Berezny

Serial No.: 09/484303

Group Art Unit: 2823

Filed: January 18, 2000

Docket: 303.648US1

Title: METHODS FOR MAKING INTEGRATED-CIRCUIT WIRING FROM  
COPPER, SILVER, GOLD, AND OTHER METALS

**COMMUNICATION CONCERNING RELATED APPLICATION(S)**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Applicants would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

<u>Serial/Patent No.</u>	<u>Filing Date</u>	<u>Attorney Docket</u>	<u>Title</u>
09/032197 6211073	February 27, 1998	303.459US1	METHODS FOR MAKING COPPER AND OTHER METAL INTERCONNECTIONS IN INTEGRATED CIRCUITS
09/817447	March 26, 2001	303.459US2	METHODS FOR MAKING COPPER AND OTHER METAL INTERCONNECTIONS IN INTEGRATED CIRCUITS
09/128859 6284656	August 4, 1998	303.473US1	COPPER METALLURGY IN INTEGRATED CIRCUITS
09/946055 6614099	September 4, 2001	303.473US2	COPPER METALLURGY IN INTEGRATED CIRCUITS
09/145012 6288442	September 1, 1998	303.505US1	INTEGRATED-CIRCUIT WITH OXIDATION-RESISTANT POLYMERIC LAYER
09/256123 6211049	February 24, 1999	303.505US2	FORMING SUBMICRON INTEGRATED-CIRCUIT WIRING FROM GOLD, SILVER, COPPER AND OTHER METALS



## COMMUNICATION CONCERNING RELATED APPLICATIONS

Serial Number: 10/179151

Filing Date: June 24, 2002

Title: INSULATORS FOR HIGH DENSITY CIRCUITS

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Dkt: 303.610US4

09/256124 6208016	February 24, 1999	303.505US3	FORMING SUBMICRON INTEGRATED-CIRCUIT WIRING FROM GOLD, SILVER, COPPER AND OTHER METALS
09/789091	February 20, 2001	303.505US4	INTEGRATED-CIRCUIT WITH OXIDATION-RESISTANT POLYMERIC LAYER
09/854540	May 14, 2001	1303.013US1	COPPER DUAL DAMASCENE INTERCONNECT TECHNOLOGY
09/488098 6429120	January 18, 2000	303.618US1	METHOD AND APPARATUS FOR MAKING INTEGRATED-CIRCUIT WIRING FROM COPPER, SILVER, GOLD, AND OTHER METALS
09/483869 6420262	January 18, 2000	303.664US1	STRUCTURES AND METHODS TO ENHANCE COPPER METALLIZATION
09/483881	January 18, 2000	303.672US1	SELECTIVE ELECTROLESS-PLATED COPPER METALLIZATION
09/484002 6376370	January 18, 2000	303.673US1	PROCESS FOR PROVIDING SEED LAYERS FOR USING ALUMINUM, COPPER, GOLD AND SILVER METALLURGY
09/584157 6674167	May 31, 2000	303.685US1	MULTILEVEL COPPER INTERCONNECT WITH DOUBLE PASSIVATION
10/117041	April 5, 2002	303.673US2	INTEGRATED CIRCUIT AND SEED LAYERS
10/196078	July 16, 2002	303.664US2	STRUCTURES AND METHODS TO ENHANCE COPPER METALLIZATION
10/196081	July 16, 2002	303.664US3	STRUCTURES AND METHODS TO ENHANCE COPPER METALLIZATION

COMMUNICATION CONCERNING RELATED APPLICATIONS

Serial Number: 10/179151

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Dkt: 303.610US4

10/211855	August 1, 2002	303.618US2	METHOD AND APPARATUS FOR MAKING INTEGRATED-CIRCUIT WIRING FROM COPPER, SILVER, GOLD, AND OTHER METALS
10/195965	July 16, 2002	303.664US4	STRUCTURES AND METHODS TO ENHANCE COPPER METALLIZATION
10/721920	November 24, 2003	303.685US2	MULTILEVEL COPPER INTERCONNECT WITH DOUBLE PASSIVATION

Respectfully submitted,

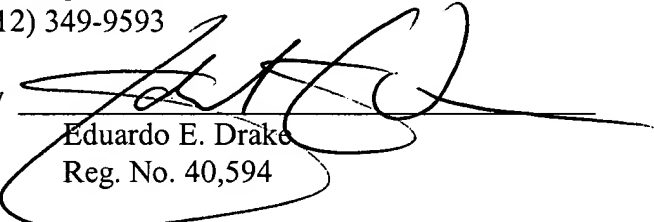
KIE Y. AHN ET AL.

By Applicants' Representatives,

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Date 12 Feb 2004

By

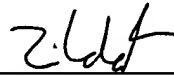
  
Eduardo E. Drake  
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Image

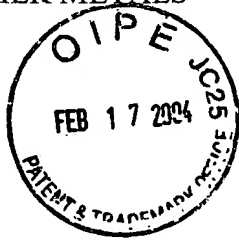
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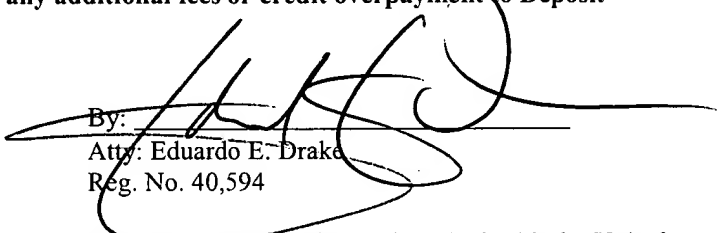
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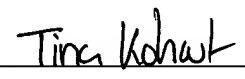
- ☒ A return postcard.
- ☒ An Amendment and Response (15 Pages).
- ☒ A Communication Concerning Related Applications (3 pgs.).
- ☒ A Supplemental Information Disclosure Statement (2 pgs.), Form 1449 (1 pg.), and copies of 6 cited documents.

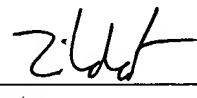
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SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.  
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